

Notice of References Cited	Application/Control No. 10/773,026	Applicant(s)/Patent Under Reexamination XIANG ET AL.	
	Examiner Heather A. Doty	Art Unit 2813	Page 1 of 1

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*	B	US-6,900,502	05-2005	Ge et al.	257/347
*	C	US-5,801,075	09-1998	Gardner et al.	438/197
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NON-PATENT DOCUMENTS

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	U	Tong et al., Semiconductor Wafer Bonding, Science and Technology, Interscience Technology, a Wiley Interscience publication, Johnson Wiley & Sons, Inc., 1998.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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